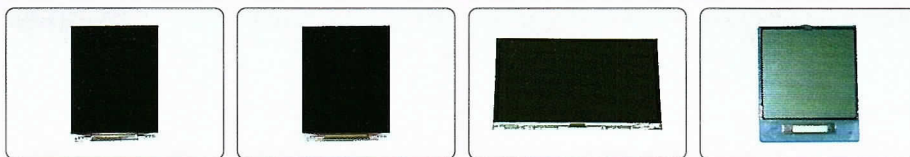


JM-8000CII

COG automatic bonding machine
COG全自动绑定机



应用展示/Application Show:



功能阐述:

JM-8000CII COG全自动绑定机主要应用于IC与LCD的ACF贴附、IC自动吸取拍照和自动预压及自动本压为一体的全自动设备。机器具备高精度影像和光学系统以及精密自动对位工作台；LCD自动上料定位装置，ACF自动检测系统和IC料盒多组装置，高速伺服马达和高刚性结构，有效确保机器生产精度和提高生产效率。

Function elaborate:

JM-8000CII is a COG full-automatic bonding machine as well as integrated equipment mainly used in the lamination of IC on LCD through ACF, automatic IC pick-up, photograph, automatic pre-bonding and main-bonding. The machine is equipped with high-precision imaging and optical systems as well as precision automatic alignment stage; multiple devices such as automatic LCD feeding and positioning device, automatic ACF detection system and IC feeding trays, high-speed servo motor and high rigid structure to effectively ensure production accuracy and improve production efficiency of the machine.

功能特点:

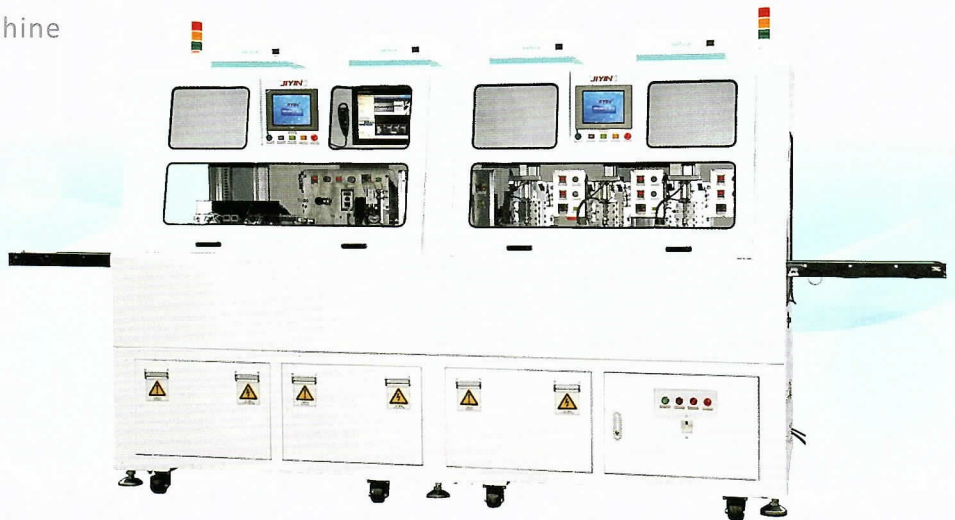
- ◎LCD上料自动定位装置
- ◎ACF自动贴附、检测系统
- ◎IC自动吸取拍照对位系统
- ◎多组IC料盒自动传送系统
- ◎IC自动本压系统
- ◎机器高刚性结构

Features:

- ◎Automatic positioning device for LCD feeding
- ◎Automatic ACF laminating and detection system
- ◎Automatic IC pick-up and photograph alignment system
- ◎Automatic transfer system with multiple IC feeding trays
- ◎Automatic IC main-bonding system
- ◎Machine structure with high rigidity

JM-8000CII

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±3μm
Equipment Precision

IC TARK
2 inch
3 inch
4 inch

Max:
10.4"
X: 234mm
Y: 178mm

CCD
automatic decimal alignment

功能特点:

- ◎LCD上料自动定位装置
- ◎ACF自动贴附、检测系统
- ◎IC自动吸取拍照对位系统
- ◎多组IC料盒自动传送系统
- ◎IC自动本压系统
- ◎机器高刚性结构

性能特徵:

- ◎LCDを投入してから自動的にCCDカメラによる位置補正装置搭載
- ◎ACF自動貼付け、検測システム
- ◎IC自動的に吸取りし、CCDカメラによる位置補正システム
- ◎多数ICトレーを自動的に運送システム
- ◎IC自動本圧着システム
- ◎高剛性な構造

产品规格:

电源	AC220V±10%, 50Hz, 8000W
操作环境	23°C±5°C, 40% to 95%, humidity with no Significant dust
工作气压	0.5~0.7Mpa (干燥气源)
模具尺寸	180×130MM (可订做)
热压头尺寸	Min: 6mm×1mm Max: 35mm×5mm
视像系统	影像自动对位系统
对位平台	自动高速X.Y. θ 伺服马达控制
程序控制	PLC控制器+触摸屏
加热方式	Constant heat
温度设置	ACF、预压: RT~200°C 本压: RT~400°C

压力设置	0.1~0.4 Mpa精密阀调节
压合时间	0~999 Seconds
LCD	Min: 3" 65mm(X边)×45mm(Y边) Max: 10.4" 234(X边)×178mm(Y边) Thic: 0.3mm~1.2mm
	Min: L3mm×W0.6mm Max: L35mm×W4mm Thic: 0.3mm~1.5mm
IC	Max: L35mm×W4mm Thic: 0.3mm~1.5mm
IC TARK	2" /3" /4"
设备精度	X: ±3μm; Y: ±3μm
机身尺寸	2150(L)×1150(W)×1800(H)mm
重量	Approx 3000kg

